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THE UNIVERSITY OF HONG KONG

How to make 10,000 V power devices in GaN and Ga₂O₃?

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Power semiconductors as pathways to carbon neutrality

nature reviews electrical engineering

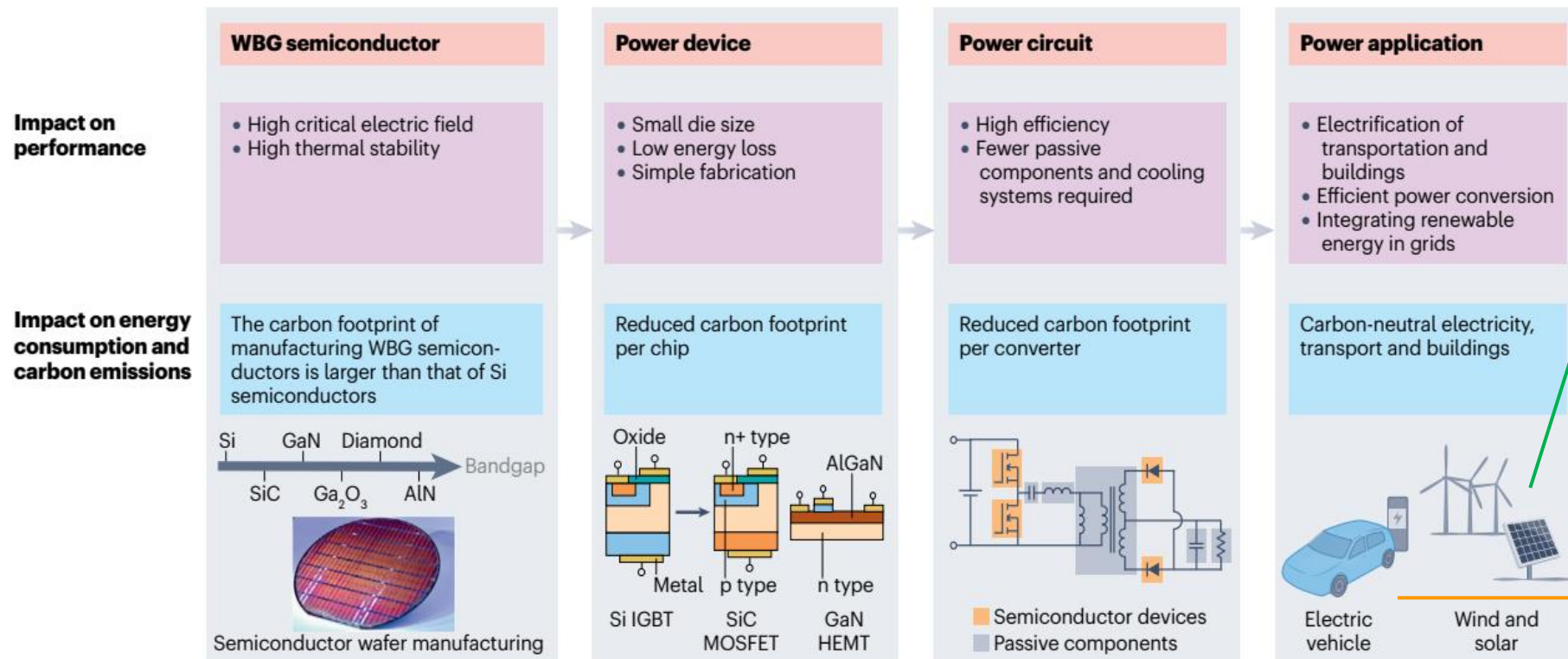
Review Article | Published: 21 January 2025

Wide-bandgap semiconductors and power electronics as pathways to carbon neutrality

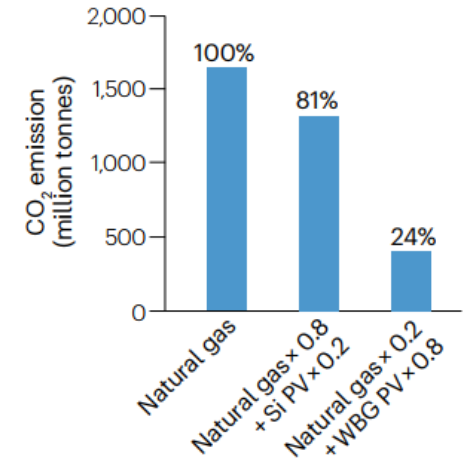
Yuhao Zhang , Dong Dong , Qiang Li , Richard Zhang, Florin Udrea & Han Wang 

Nature Reviews Electrical Engineering **2**, 155–172 (2025) | [Cite this article](#)

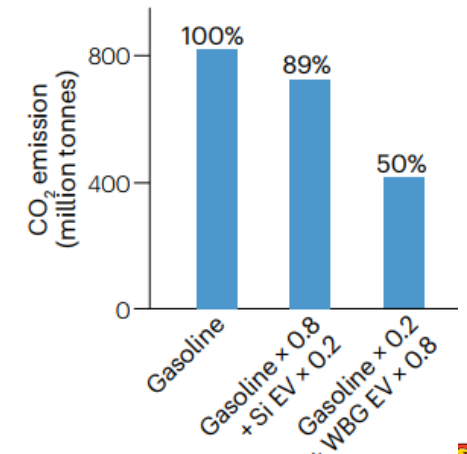
WBG replacing Si can enable an annual carbon saving of at least 20 million tonnes in the USA – annual emissions of 4 million gasoline passenger vehicles



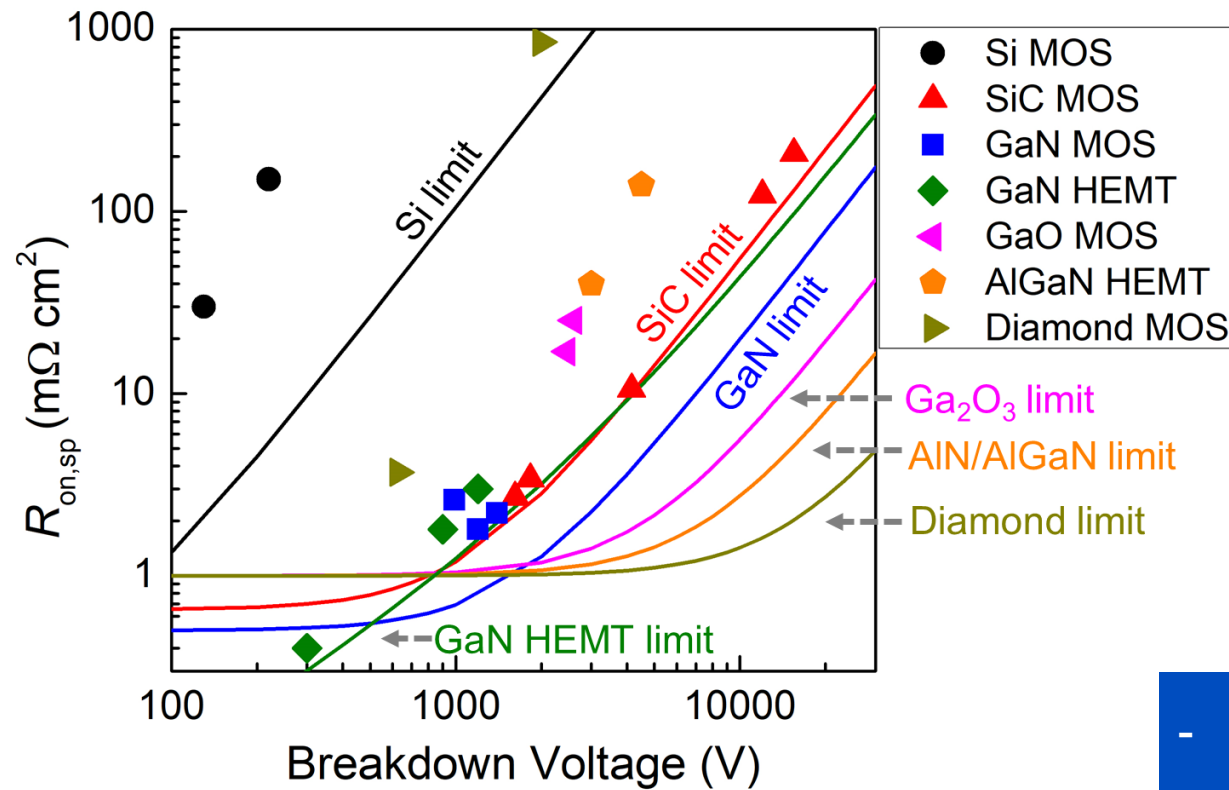
electricity generation



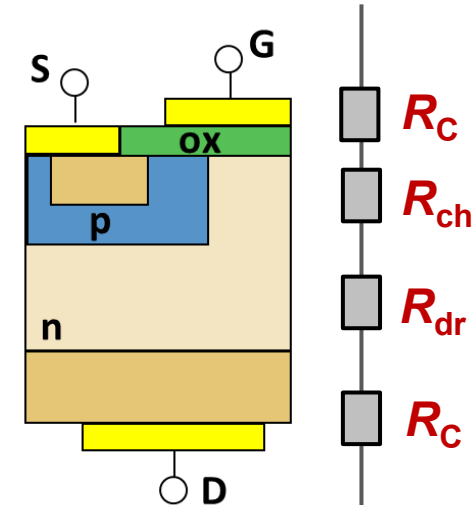
electric vehicles



Challenges for WBG devices going up



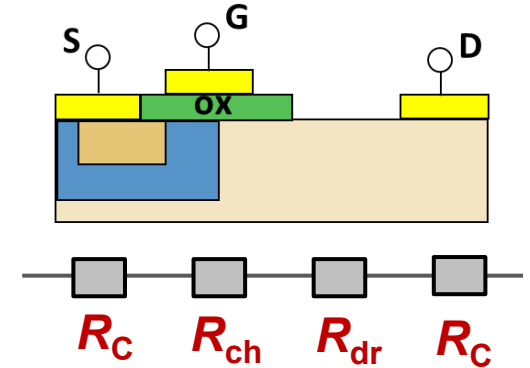
Vertical FET



$$R_{ON,SP} = R_C + R_{ch} + \frac{4BV^2}{\epsilon\mu E_C^3}$$

- Thick lowly-doped drift region
- Low material/device yield
- High material cost

Lateral FET

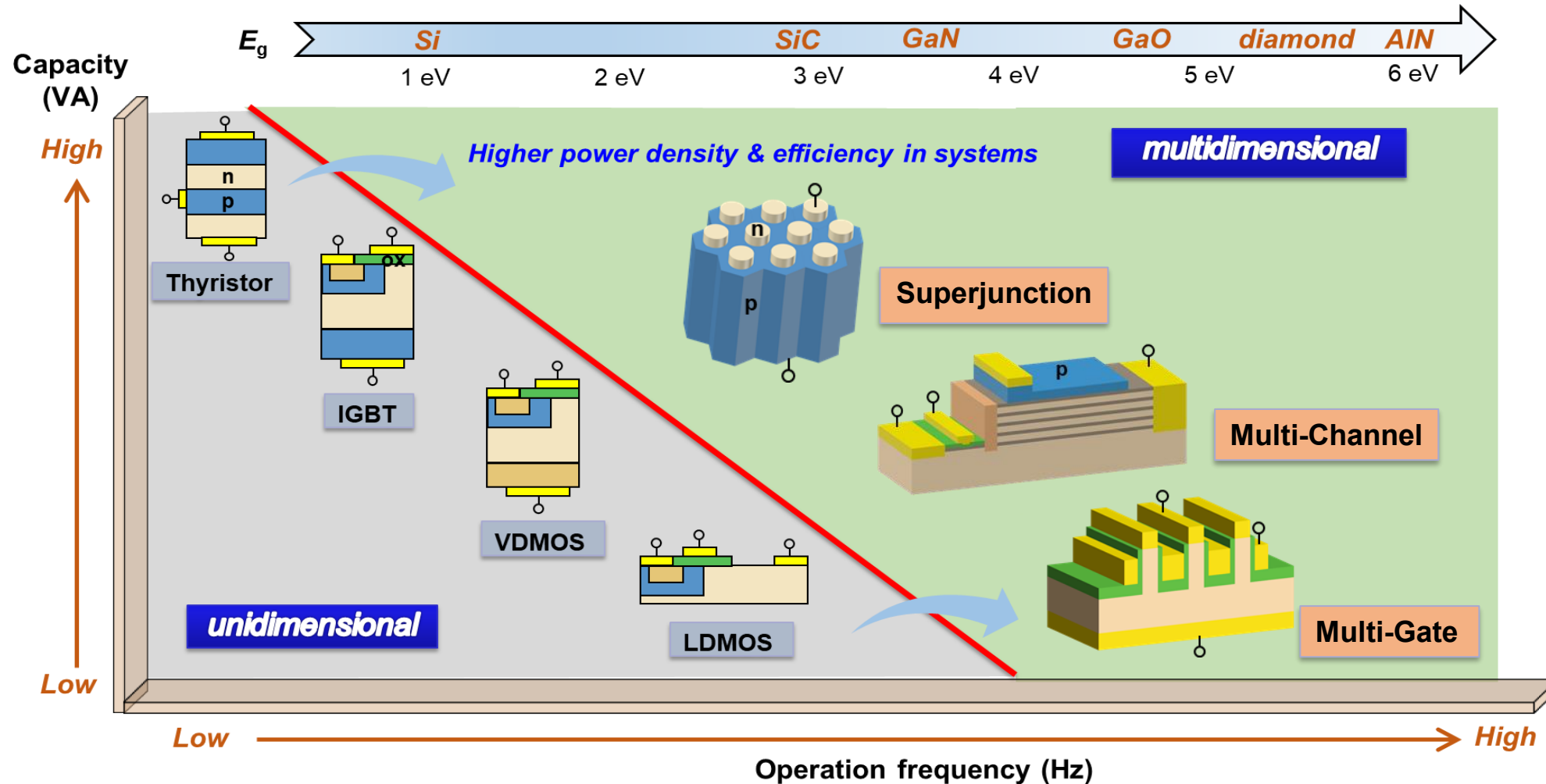


$$R_{ON,SP} = R_C + R_{CH} \frac{BV}{\eta E_C} + \frac{BV^2}{qn_{2D}\mu_{2D}\eta^2 E_C^2}$$

- Non-uniform E-field
- Difficult BV upscaling
- High $R_{DS,ON}$

Y. Zhang, F. Udrea, H. Wang, **Nature Electronics**, 5, 723, Nov. 2022

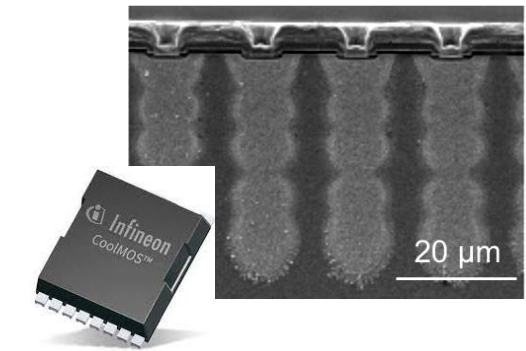
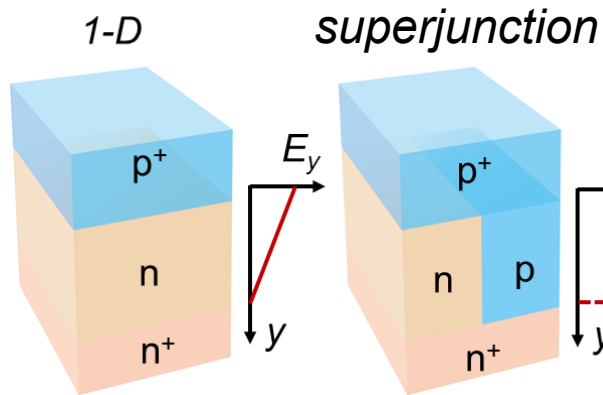
Solution – Multidimensional power devices



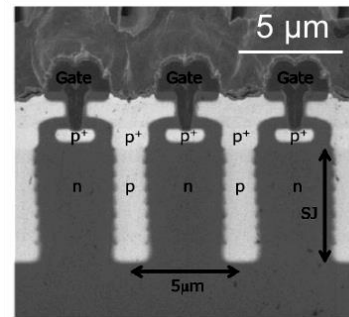
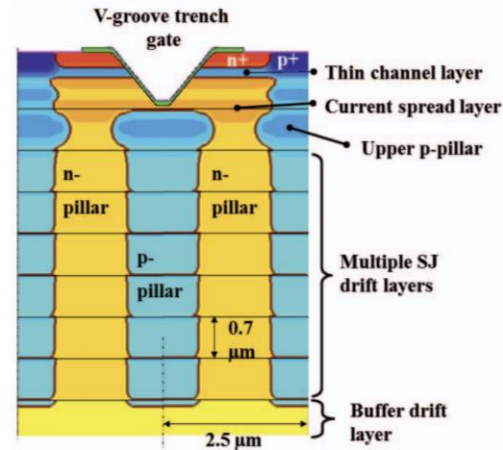
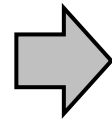
Y. Zhang, F. Udrea,
H. Wang, **Nature
Electronics**, 5, 723,
Nov. 2022

- electrostatic engineering in at least one additional geometrical dimension
- break the capacity-frequency and $R_{ON,SP} \sim BV$ trade-off

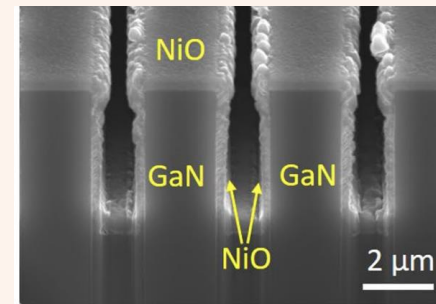
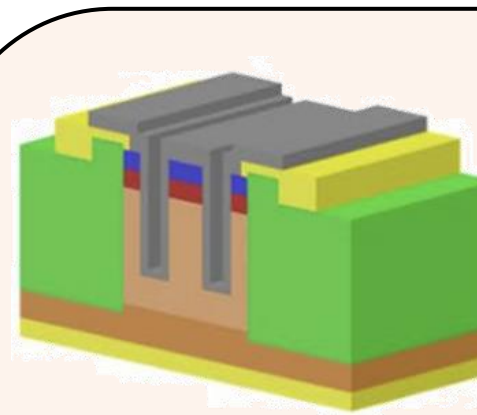
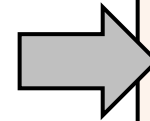
Vertical superjunction: from Si to WBG and UWBG



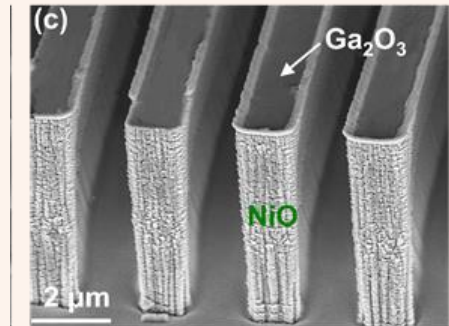
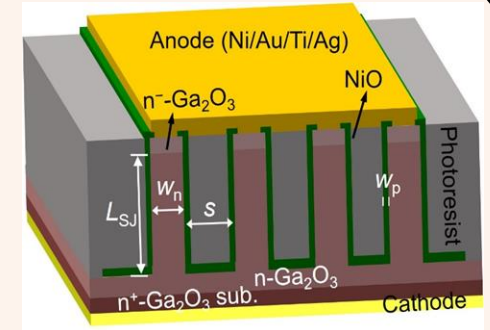
Si superjunction
commercial since 1998
~\$1billion market



SiC superjunction
1st demo in 2016-2018
1.2kV, 0.63mΩ·cm²



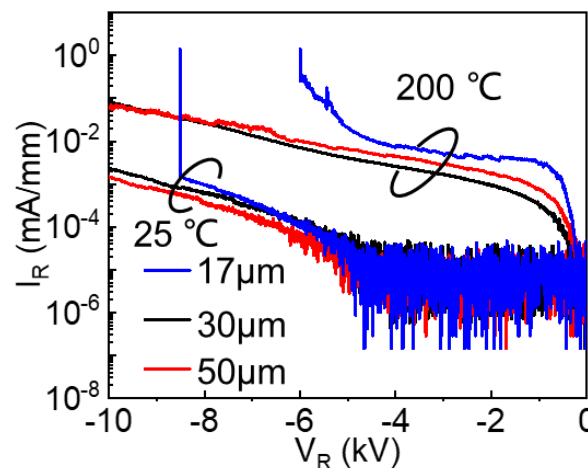
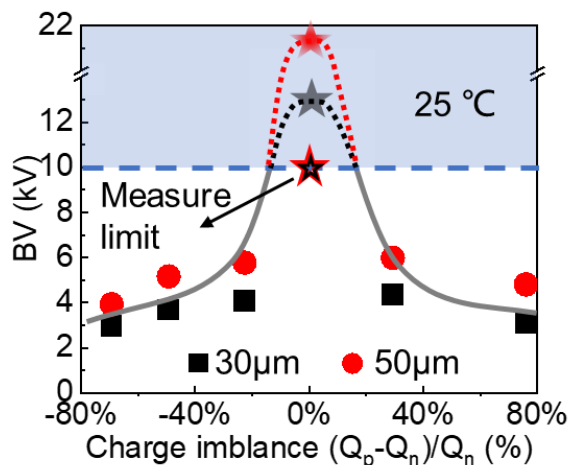
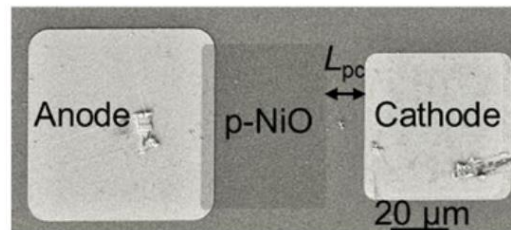
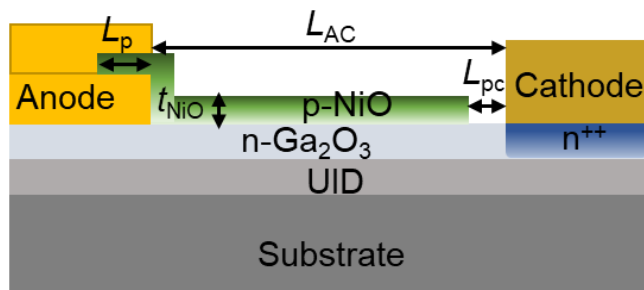
GaN superjunction
1st demo (IEDM2022)
1.1kV, 0.3mΩ·cm²



Ga₂O₃ superjunction
1st demo (IEDM2023)
2kV, 0.7mΩ·cm²

[1] T. Masuda et al., "0.63 mΩ·cm², 1170 V 4H-SiC Super Junction V-Groove Trench MOSFETM," IEDM, 2018. [2] M. Xiao et al., "First demonstration of vertical superjunction diode in GaN", IEDM, 2022. [3] Y. Qin et al., "2 kV, 0.7 mΩ·cm² vertical Ga₂O₃ superjunction Schottky rectifier with dynamic robustness," IEDM 2023.

Lateral superjunction: first 10kV Ga₂O₃ device



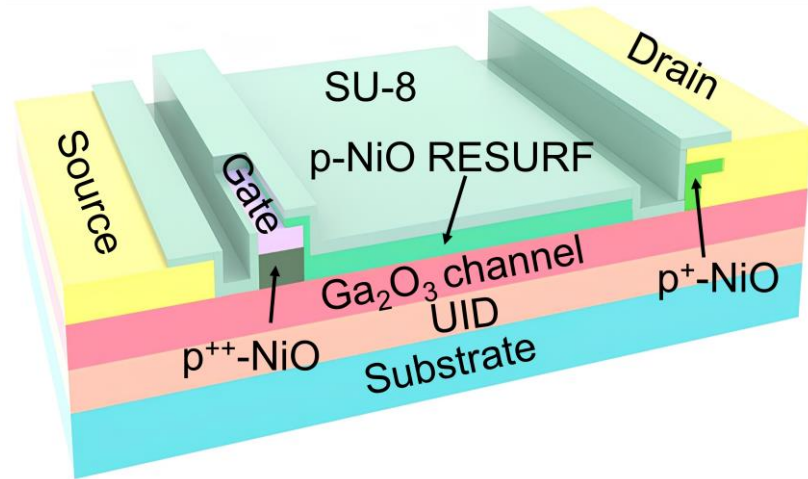
Device	Ave. E-field (MV/cm)
Ga₂O₃ RESURF SBD	4.7
Ga ₂ O ₃ SBD	1.1
AlGaO/NiO PND	0.5
Ga ₂ O ₃ MOSFET	1-1.4
GaN SBD	0.94
GaN HEMT	1.1
AlGaN HEMT	1.1
Diamond SBD	0.57

- 10 kV Ga₂O₃ SBD operational at 200 °C
- NiO superjunction: *BV* shows strong modulation by charge balance
- Record high lateral E-field in kilovolts devices

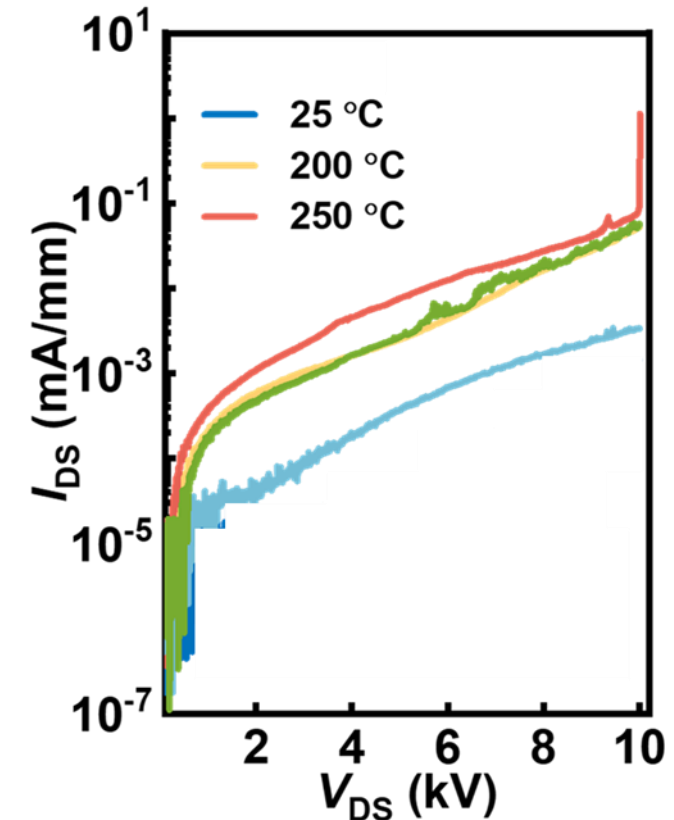
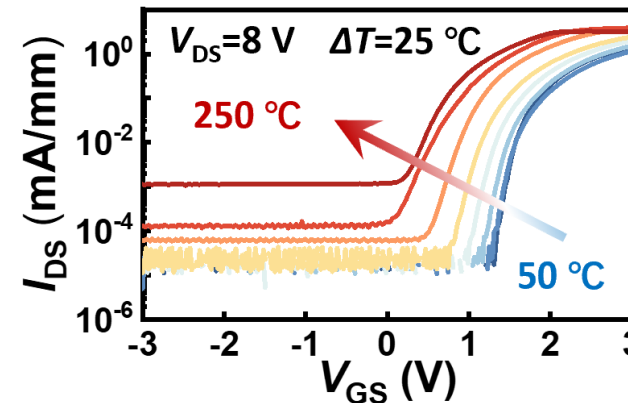
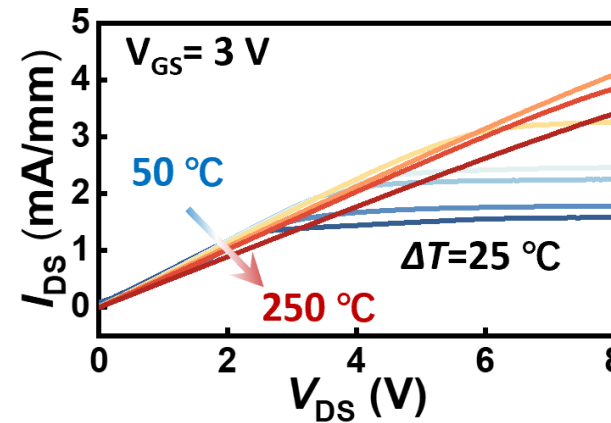
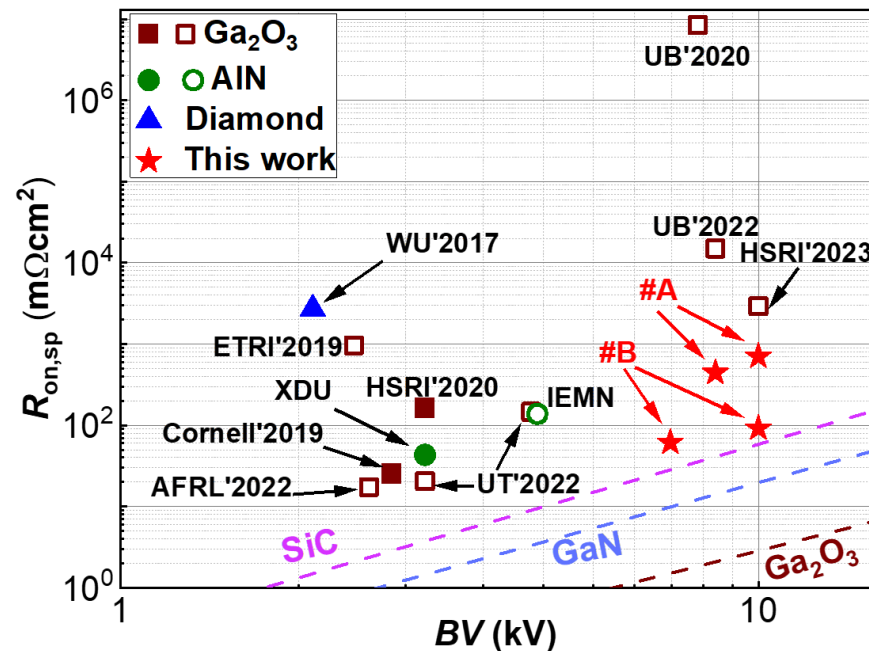
[1] Y. Qin *et al.*, **EDL**, 2023; [2] Y. Ma, Y. Qin, M. Porter *et al.*, **Adv. Electron. Mater.** 2023.



10 kV Ga₂O₃ E-mode superjunction JFET operational up to 250 °C



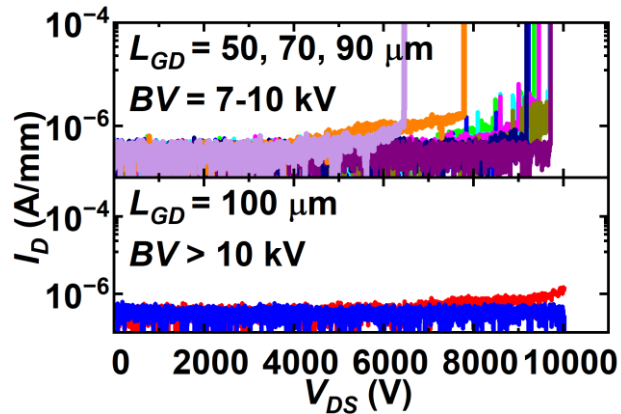
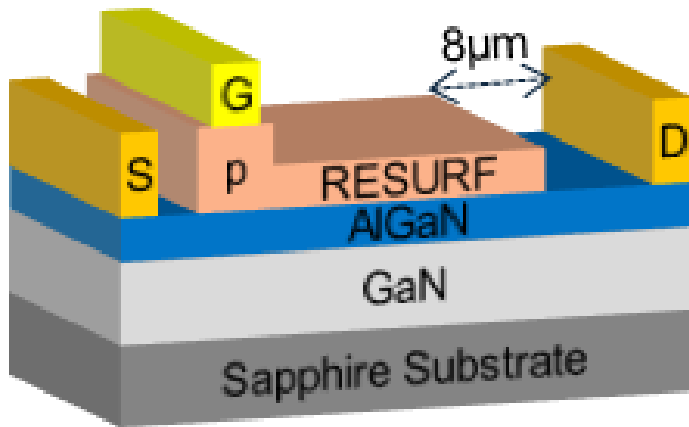
Filled symbol: E-mode Empty symbol: D-mode



- Junction gate + charge-balance RESURF + hybrid drain
- Different NiO doping optimized for three structures
- E-mode operation + 10 kV blocking @ 250 °C

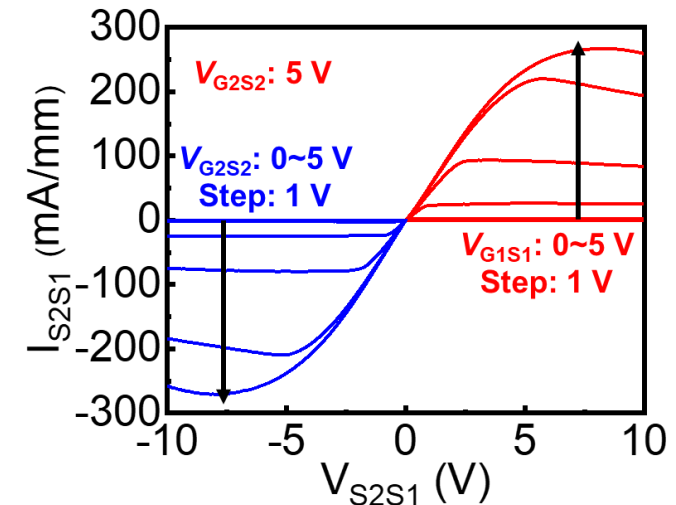
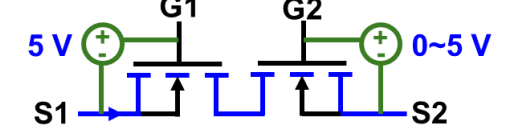
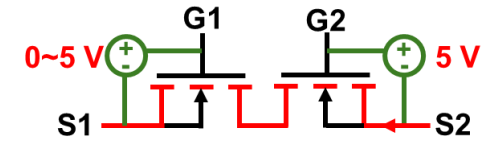
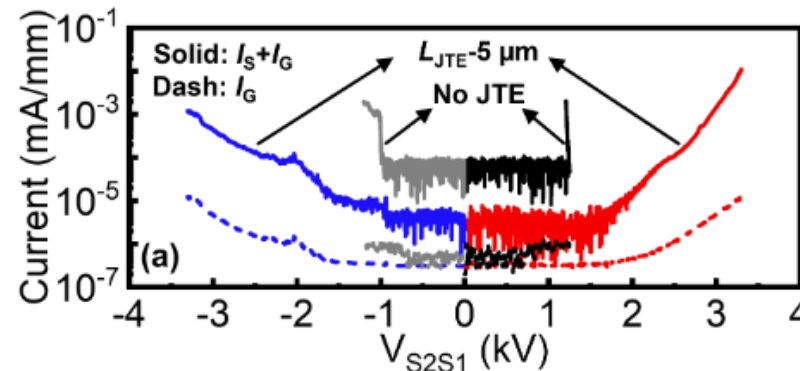
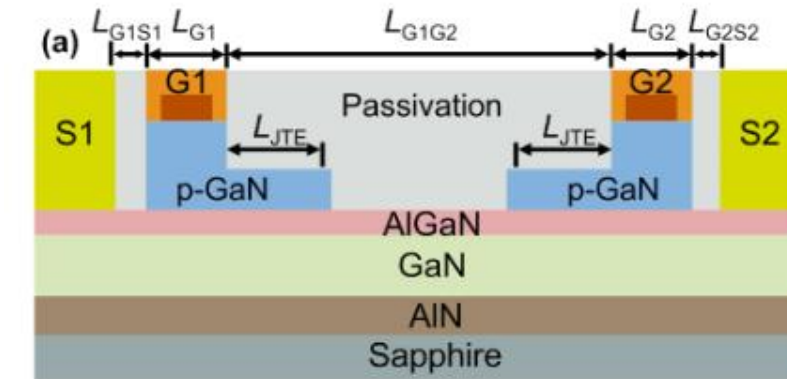
Y. Qin *et al.*, IEDM 24 (IEDM Technical Highlight)

10 kV GaN superjunction HEMT and Monolithic Bidirectional Switch



- BV upscaling enabled by charge-balance between p-GaN and AlGaIn/GaN
- 10 kV, 70 mΩ·cm² E-mode GaN HEMT

Y. Guo *et al.*, under review

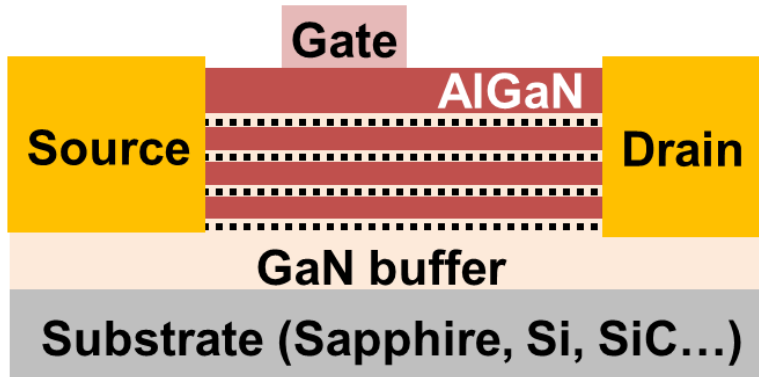


- Dual p-GaN JFET improves E-field management
- 3.3 kV, 5.6 mΩ·cm² E-mode GaN monolithic bidirectional HEMT

Y. Guo *et al.*, EDL 2025



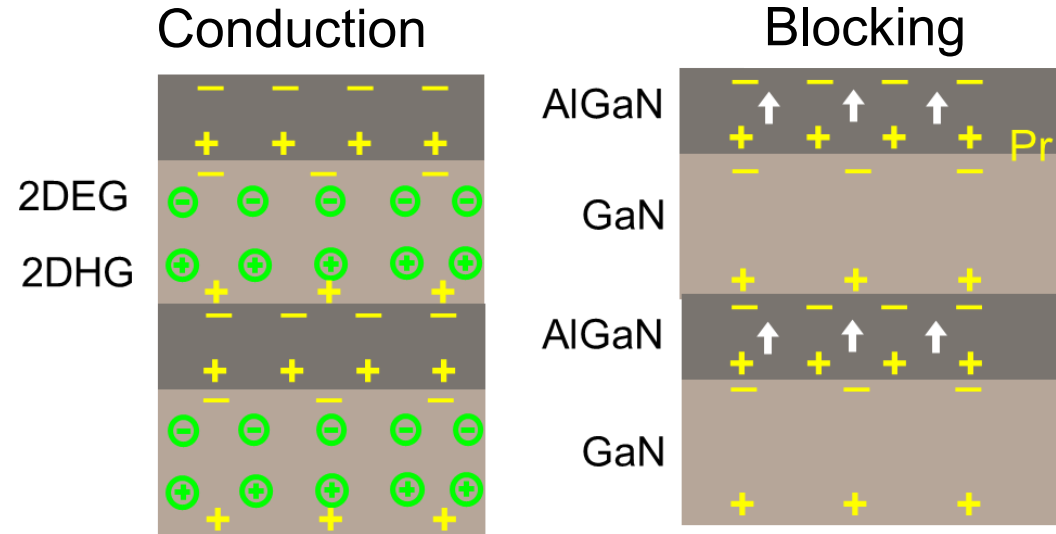
Multi-channel: lateral polarization superjunction



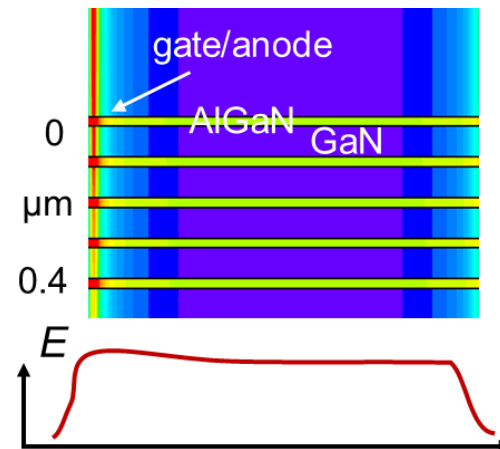
- ✓ High current capability
- ✓ Low R_{on} for HV
- ✓ Ideally, a natural superjunction

New challenges:

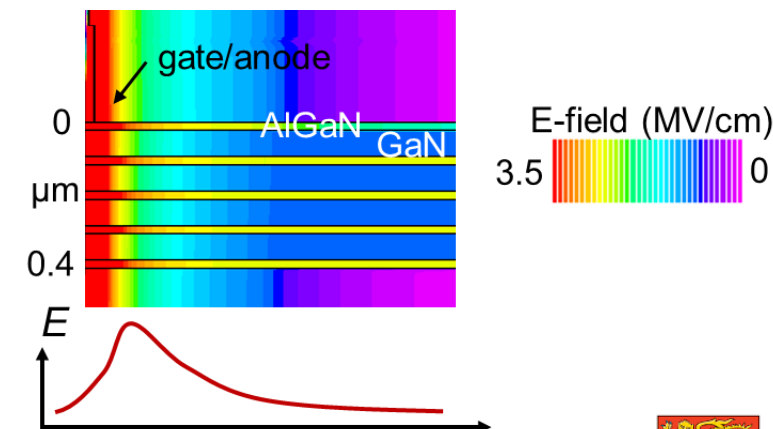
- (non-ideal) E-field management
- E-mode gate



Ideal multi-channel



Multi-channel w/ net charge

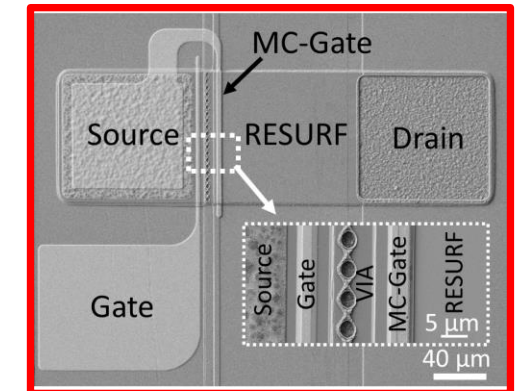
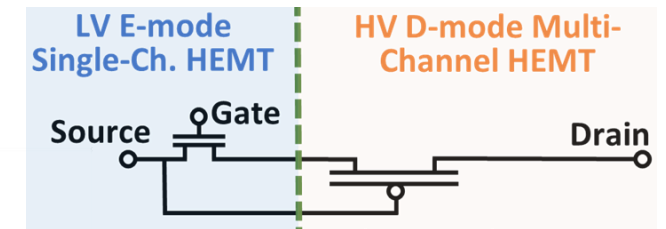
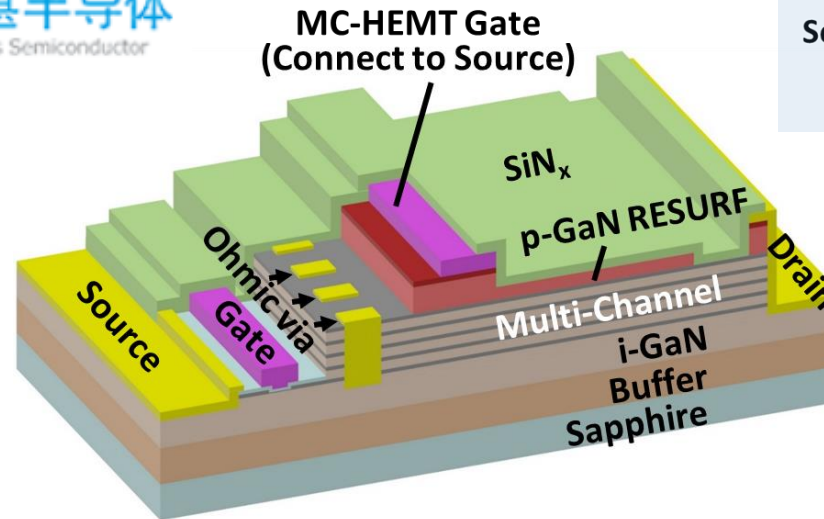
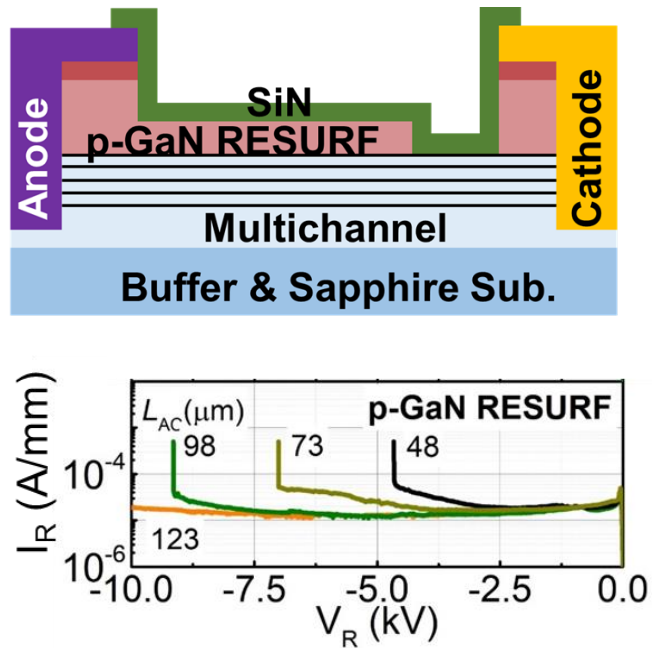


Y. Zhang, F. Udrea, H. Wang, **Nature Electronics**, 5, 723, Nov. 2022

Multi-channel: enabling 10kV GaN with $R_{ON,SP}$ 2.5x lower than SiC

- 4-inch wafer, **five channels**, R_{SH} 120 Ω /sq
- p-GaN charge balance with multi-channel (**superjunction design**)
- $BV > 10$ kV, $R_{ON,SP} = 39$ m Ω ·cm²

- Multi-Channel Monolithic-Cascode HEMT (MC²-HEMT)
- $V_{TH} > 1.5$ V; $I_{SAT} > 300$ mA/mm; $R_{ON,SP}$ of 40 m Ω ·cm²
- **Best FOM in 6.5kV+ power transistors**

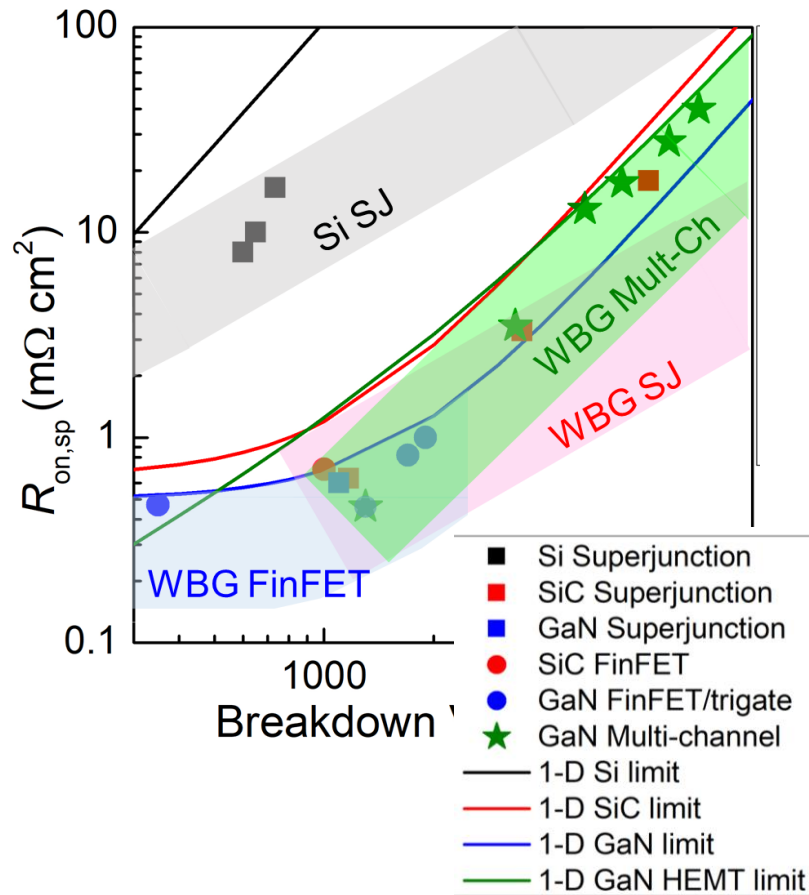



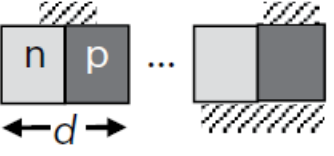
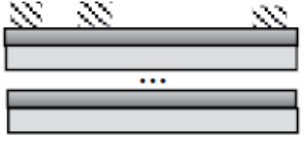
M. Xiao *et al.*, "10 kV, 39 m Ω ·cm² Multi-channel AlGaIn/GaN Schottky barrier diodes," *IEEE Electron Device Letters*, 2021.

M. Xiao *et al.*, "Multi-Channel Monolithic-Cascode HEMT (MC²-HEMT): A New GaN Power Switch up to 10 kV," *IEDM*, 2021.
(**IEDM Technical Highlights**, Nature Electronics Coverage)



Multidimensional devices: new limits and new scaling laws



Drift region design	1D	2D superjunction	Multi-channel (PSJ)
Structure			 } N channels
Performance limit	$R_{ON,SP} = \frac{4}{\epsilon\mu E_C^3} BV^2$	$R_{ON,SP} = \frac{4d}{\epsilon\mu E_C^2} BV$	$R_{ON,SP} = \frac{BV^2}{NqE_C^2 n_{2D} \sum_{e,h} \mu_{2D}}$
Scaling parameter	NA	Cell pitch (d)	Channel number (N)
Scaling limit	NA	$d = \frac{50E_g}{9qE_C}$	Process and technology related
Minimum specific on-resistance	$\frac{4BV^2}{\epsilon\mu E_C^3}$	$\frac{20E_g BV}{q\epsilon\mu E_C^3}$	—
Material FOM	$\epsilon\mu E_C^3$	$\epsilon\mu E_C^{2.5}$	$E_C^2 n_{2D} \sum_{e,h} \mu_{2D}$

- Allow geometrical scaling in power devices (limit: line -> band)
- Baliga's FOM is no longer suitable for benchmarking multidimensional power devices

Y. Zhang, F. Udrea, H. Wang, "Multidimensional device architectures for efficient power electronics," *Nature Electronics*, 2022

Key takeaway

- The renaissance of lateral devices for high-voltage applications (significant cost reduction)
- Multidimensional architectures – such as superjunction and multichannel – are essential;
e.g., multichannel GaN HEMT enables $R_{on,sp}$ 2.5x lower than SiC MOSFET at 10 kV
- UWBG can enable high E-field and high-temperature operation

